

ABSTRACT OF THE DISCLOSURE

A semiconductor card is made by a disclosed method which, in one molding step, forms a plastic body on a substrate attached to a surrounding frame by narrow connecting segments spanning a peripheral opening. The connecting segments are motivated downward by pins outside of the card periphery, holding the substrate against a lower level of the mold cavity during molding. Molded wings extending laterally from the card periphery are also formed. Following molding and curing, the casting is removed and the card singulated by excising the wings from the card. The resulting card has smooth edge surfaces and precise dimensions. Separate glob top encapsulation is avoided.

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